



Material Content Data Sheet



Halogen-Free

Sales Product Name	SPD04N80C3	Issued	27. April 2022
MA#	MA005728551		
Package	PG-TO252-3-35	Weight*	323.70 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.894	1.20	1.20	12028	12028
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		164	
	non noble metal	iron	7439-89-6	0.177	0.05		547	
	non noble metal	copper	7440-50-8	176.899	54.65	54.72	546483	547194
wire	non noble metal	aluminium	7429-90-5	0.632	0.20	0.20	1953	1953
encapsulation	organic material	carbon black	1333-86-4	0.405	0.12		1250	
	plastics	epoxy resin	-	15.776	4.87		48735	
	inorganic material	silicondioxide	60676-86-0	118.654	36.66	41.65	366551	416536
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11843	11843
solder	non noble metal	tin	7440-31-5	0.068	0.02		209	
	noble metal	silver	7440-22-4	0.085	0.03		261	
	non noble metal	lead	7439-92-1	3.229	1.00	1.05	9976	10446
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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